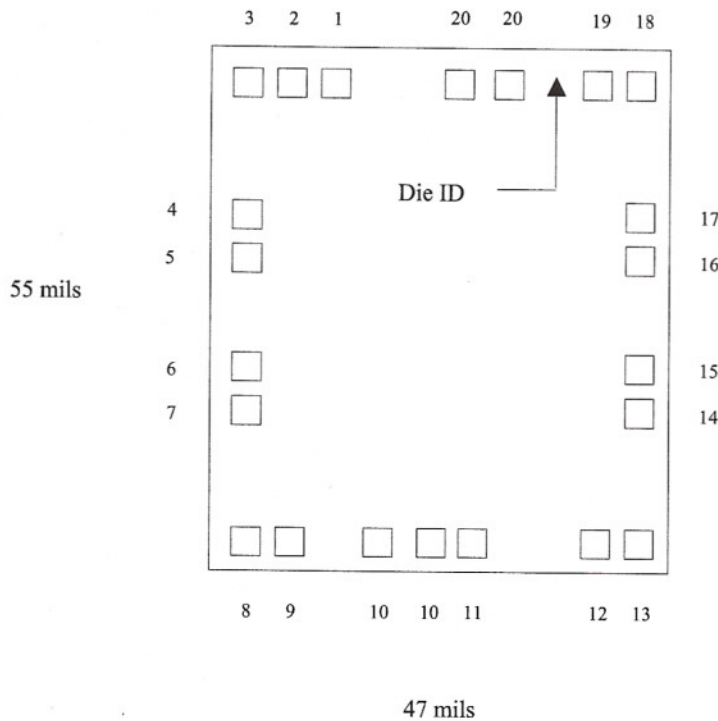




# Sierra Components, Inc.

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 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



### PAD FUNCTION

- 1 N.1G
- 2 1A1
- 3 2Y4
- 4 1A2
- 5 2Y3
- 6 1A3
- 7 2Y2
- 8 1A4
- 9 2Y1
- 10 GND (2 bond pads)
- 11 2A1
- 12 1Y4
- 13 2A2
- 14 1Y3
- 15 2A3
- 16 1Y2
- 17 2A4
- 18 1Y1
- 19 N.2G
- 20 V<sub>CC</sub> (2 bond pads)

**Topside Metal: Aluminum**  
**Backside Metal: Silicon**  
**Backside Potential: Grnd**  
**Bond Pad Size: .004" min.**  
**Mask Ref:**

APPROVED BY: C Dawson

DIE SIZE : .047" X .055"

DATE: 11/10/05

MFG: Fairchild

THICKNESS: .014"

Part # 54AC244